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Details

Product Status	Not For New Designs
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	POR, PWM, WDT
Number of I/O	24
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	-
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To obtain the most recent version of this datasheet, please check at www.st.com>products>technical literature>datasheet.

Please also pay special attention to the Section "KNOWN LIMITATIONS" on page 154.

Table 2. Hardware Register Map

Address	Block	Register Label	Register Name	Reset Status	Remarks				
0000h	Port A ²⁾	PADR	Port A Data Register	00h ¹⁾	R/W				
0001h		PADDR	Port A Data Direction Register	00h	R/W				
0002h		PAOR	Port A Option Register	00h	R/W				
0003h	Port B ²⁾	PBDR	Port B Data Register	00h ¹⁾	R/W				
0004h		PBDDR	Port B Data Direction Register	00h	R/W				
0005h		PBOR	Port B Option Register	00h	R/W				
0006h	Port C	PCDR	Port C Data Register	00h ¹⁾	R/W				
0007h		PCDDR	Port C Data Direction Register	00h	R/W				
0008h		PCOR	Port C Option Register	00h	R/W				
0009h	Port D ²⁾	PDADR	Port D Data Register	00h ¹⁾	R/W				
000Ah		PDDDR	Port D Data Direction Register	00h	R/W				
000Bh		PDOR	Port D Option Register	00h	R/W				
000Ch	Port E ²⁾	PEDR	Port E Data Register	00h ¹⁾	R/W				
000Dh		PEDDR	Port E Data Direction Register	00h	R/W ²⁾				
000Eh		PEOR	Port E Option Register	00h	R/W ²⁾				
000Fh	Port F ²⁾	PFDR	Port F Data Register	00h ¹⁾	R/W				
0010h		PFDDR	Port F Data Direction Register	00h	R/W				
0011h		PFOR	Port F Option Register	00h	R/W				
0012h to 0020h			Reserved Area (15 Bytes)						
0021h	SPI	SPIDR	SPI Data I/O Register	xxh	R/W				
0022h		SPICR	SPI Control Register	0xh	R/W				
0023h		SPICSR	SPI Control/Status Register	00h	R/W				
0024h	ПС	ISPR0	Interrupt Software Priority Register 0	FFh	R/W				
0025h		ISPR1	Interrupt Software Priority Register 1	FFh	R/W				
0026h		ISPR2	Interrupt Software Priority Register 2	FFh	R/W				
0027h		ISPR3	Interrupt Software Priority Register 3	FFh	R/W				
0028h		EICR	External Interrupt Control Register	00h	R/W				
0029h	FLASH	FCSR	Flash Control/Status Register	00h	R/W				
002Ah	WATCHDOG	WDGCR	Watchdog Control Register	7Fh	R/W				
002Bh			Reserved Area (1 Byte)						
002Ch	MCC	MCCSR	Main Clock Control / Status Register	00h	R/W				
002Dh		MCCBCR	Main Clock Controller: Beep Control Register	00h	R/W				
002Eh to 0030h	Reserved Area (3 Bytes)								



CENTRAL PROCESSING UNIT (Cont'd)

Condition Code Register (CC)

Read/Write

Reset Value: 111x1xxx



The 8-bit Condition Code register contains the interrupt masks and four flags representative of the result of the instruction just executed. This register can also be handled by the PUSH and POP instructions.

These bits can be individually tested and/or controlled by specific instructions.

Arithmetic Management Bits

Bit $4 = \mathbf{H}$ Half carry.

This bit is set by hardware when a carry occurs between bits 3 and 4 of the ALU during an ADD or ADC instructions. It is reset by hardware during the same instructions.

0: No half carry has occurred.

1: A half carry has occurred.

This bit is tested using the JRH or JRNH instruction. The H bit is useful in BCD arithmetic subroutines.

Bit 2 = N Negative.

This bit is set and cleared by hardware. It is representative of the result sign of the last arithmetic, logical or data manipulation. It's a copy of the result 7^{th} bit.

0: The result of the last operation is positive or null.

- 1: The result of the last operation is negative
- (i.e. the most significant bit is a logic 1).

This bit is accessed by the JRMI and JRPL instructions.

Bit 1 = **Z** Zero.

This bit is set and cleared by hardware. This bit indicates that the result of the last arithmetic, logical or data manipulation is zero.

0: The result of the last operation is different from zero.

1: The result of the last operation is zero.

This bit is accessed by the JREQ and JRNE test instructions.

Bit 0 = C Carry/borrow.

This bit is set and cleared by hardware and software. It indicates an overflow or an underflow has occurred during the last arithmetic operation.

0: No overflow or underflow has occurred.

1: An overflow or underflow has occurred.

This bit is driven by the SCF and RCF instructions and tested by the JRC and JRNC instructions. It is also affected by the "bit test and branch", shift and rotate instructions.

Interrupt Management Bits

Bit 5,3 = 11, 10 Interrupt

The combination of the I1 and I0 bits gives the current interrupt software priority.

Interrupt Software Priority	11	10
Level 0 (main)	1	0
Level 1	0	1
Level 2	0	0
Level 3 (= interrupt disable)	1	1

These two bits are set/cleared by hardware when entering in interrupt. The loaded value is given by the corresponding bits in the interrupt software priority registers (IxSPR). They can be also set/ cleared by software with the RIM, SIM, IRET, HALT, WFI and PUSH/POP instructions.

See the interrupt management chapter for more details.

RESET SEQUENCE MANAGER (Cont'd)

The RESET pin is an asynchronous signal which plays a major role in EMS performance. In a noisy environment, it is recommended to follow the guidelines mentioned in the electrical characteristics section.

6.3.3 External Power-On RESET

To start up the microcontroller correctly, the user must ensure by means of an external reset circuit that the reset signal is held low until V_{DD} is over the minimum level specified for the selected f_{OSC} frequency.

A proper reset signal for a slow rising V_{DD} supply can generally be provided by an external RC network connected to the RESET pin.

6.3.4 Internal Watchdog RESET

The RESET sequence generated by a internal Watchdog counter overflow is shown in Figure 14.

Starting from the Watchdog counter underflow, the device RESET pin acts as an output that is pulled low during at least $t_{w(RSTL)out}$.



Figure 14. RESET Sequences

6.4 SYSTEM INTEGRITY MANAGEMENT

6.4.1 Register Description

SYSTEM INTEGRITY (SI) CONTROL/STATUS REGISTER (SICSR)

Read/Write

Reset Value: 0000 000x (00h)

7							0
0	0	0	0	0	0	0	WDG RF

Bits 7:1 = Reserved, must be kept cleared.

Bit 0 = WDGRF Watchdog reset flag

This bit indicates that the last Reset was generated by the Watchdog peripheral. It is set by hardware (watchdog reset) and cleared by software (writing zero).

I/O PORTS (Cont'd)

9.5.1 I/O Port Implementation

The I/O port register configurations are summarised as follows.

Standard Ports

PA5:4, PC7:0, PD5:0, PE1:0, PF7:6, 4

MODE	DDR	OR
floating input	0	0
pull-up input	0	1
open drain output	1	0
push-pull output	1	1

Interrupt Ports

PB4, PB2:0, PF1:0 (with pull-up)

MODE	DDR	OR
floating input	0	0
pull-up interrupt input	0	1
open drain output	1	0
push-pull output	1	1

Table 12. Port Configuration

PA3, PB3, PF2 (without pull-up)

MODE	DDR	OR
floating input	0	0
floating interrupt input	0	1
open drain output	1	0
push-pull output	1	1

True Open Drain Ports PA7:6

MODE	DDR
floating input	0
open drain (high sink ports)	1

Dort	Din nomo	I	Output		
Port	Pin name	OR = 0	OR = 1	OR = 0	OR = 1
	PA7:6	fl	pating	true op	en-drain
Port A	PA5:4	floating	pull-up	open drain	push-pull
	PA3	floating	floating interrupt	open drain	push-pull
PB3		floating	floating interrupt	open drain	push-pull
FUILE	PB4, PB2:0	floating	pull-up interrupt	open drain	push-pull
Port C	PC7:0	floating	pull-up	open drain	push-pull
Port D	PD5:0	floating	pull-up	open drain	push-pull
Port E	PE1:0	floating	pull-up	open drain	push-pull
	PF7:6, 4	floating	pull-up	open drain	push-pull
Port F	PF2	floating	floating interrupt	open drain	push-pull
	PF1:0	floating	pull-up interrupt	open drain	push-pull

10 ON-CHIP PERIPHERALS

10.1 WATCHDOG TIMER (WDG)

10.1.1 Introduction

The Watchdog timer is used to detect the occurrence of a software fault, usually generated by external interference or by unforeseen logical conditions, which causes the application program to abandon its normal sequence. The Watchdog circuit generates an MCU reset on expiry of a programmed time period, unless the program refreshes the counter's contents before the T6 bit becomes cleared.

10.1.2 Main Features

- Programmable free-running downcounter
- Programmable reset
- Reset (if watchdog activated) when the T6 bit reaches zero
- HALT Optional reset on instruction (configurable by option byte)
- Hardware Watchdog selectable by option byte

10.1.3 Functional Description

The counter value stored in the Watchdog Control register (WDGCR bits T[6:0]), is decremented every 16384 f_{OSC2} cycles (approx.), and the length of the timeout period can be programmed by the user in 64 increments.

If the watchdog is activated (the WDGA bit is set) and when the 7-bit timer (bits T[6:0]) rolls over from 40h to 3Fh (T6 becomes cleared), it initiates a reset cycle pulling low the reset pin for typically 30µs.

The application program must write in the WDGCR register at regular intervals during normal operation to prevent an MCU reset. This downcounter is free-running: it counts down even if the watchdog is disabled. The value to be stored in the WDGCR register must be between FFh and C0h:

- The WDGA bit is set (watchdog enabled)
- The T6 bit is set to prevent generating an immediate reset
- The T[5:0] bits contain the number of increments which represents the time delay before the watchdog produces a reset (see Figure 30. Approximate Timeout Duration). The timing varies between a minimum and a maximum value due to the unknown status of the prescaler when writing to the WDGCR register (see Figure 31).

Following a reset, the watchdog is disabled. Once activated it cannot be disabled, except by a reset.

The T6 bit can be used to generate a software reset (the WDGA bit is set and the T6 bit is cleared).

If the watchdog is activated, the HALT instruction will generate a Reset.



Figure 29. Watchdog Block Diagram

10.3 16-BIT TIMER

10.3.1 Introduction

The timer consists of a 16-bit free-running counter driven by a programmable prescaler.

It may be used for a variety of purposes, including pulse length measurement of up to two input signals (*input capture*) or generation of up to two output waveforms (*output compare* and *PWM*).

Pulse lengths and waveform periods can be modulated from a few microseconds to several milliseconds using the timer prescaler and the CPU clock prescaler.

Some ST7 devices have two on-chip 16-bit timers. They are completely independent, and do not share any resources. They are synchronized after a MCU reset as long as the timer clock frequencies are not modified.

This description covers one or two 16-bit timers. In ST7 devices with two timers, register names are prefixed with TA (Timer A) or TB (Timer B).

10.3.2 Main Features

- Programmable prescaler: f_{CPU} divided by 2, 4 or 8.
- Overflow status flag and maskable interrupt
- External clock input (must be at least 4 times slower than the CPU clock speed) with the choice of active edge
- 1 or 2 Output Compare functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated programmable signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- 1 or 2 Input Capture functions each with:
 - 2 dedicated 16-bit registers
 - 2 dedicated active edge selection signals
 - 2 dedicated status flags
 - 1 dedicated maskable interrupt
- Pulse width modulation mode (PWM)
- One pulse mode
- Reduced Power Mode
- 5 alternate functions on I/O ports (ICAP1, ICAP2, OCMP1, OCMP2, EXTCLK)*

The Block Diagram is shown in Figure 33.

*Note: Some timer pins may not be available (not bonded) in some ST7 devices. Refer to the device pin out description.

When reading an input signal on a non-bonded pin, the value will always be '1'.

10.3.3 Functional Description

10.3.3.1 Counter

The main block of the Programmable Timer is a 16-bit free running upcounter and its associated 16-bit registers. The 16-bit registers are made up of two 8-bit registers called high & low.

Counter Register (CR):

- Counter High Register (CHR) is the most significant byte (MS Byte).
- Counter Low Register (CLR) is the least significant byte (LS Byte).

Alternate Counter Register (ACR)

- Alternate Counter High Register (ACHR) is the most significant byte (MS Byte).
- Alternate Counter Low Register (ACLR) is the least significant byte (LS Byte).

These two read-only 16-bit registers contain the same value but with the difference that reading the ACLR register does not clear the TOF bit (Timer overflow flag), located in the Status register, (SR), (see note at the end of paragraph titled 16-bit read sequence).

Writing in the CLR register or ACLR register resets the free running counter to the FFFCh value.

Both counters have a reset value of FFFCh (this is the only value which is reloaded in the 16-bit timer). The reset value of both counters is also FFFCh in One Pulse mode and PWM mode.

The timer clock depends on the clock control bits of the CR2 register, as illustrated in Table 16 Clock Control Bits. The value in the counter register repeats every 131072, 262144 or 524288 CPU clock cycles depending on the CC[1:0] bits.

The timer frequency can be $f_{CPU}/2$, $f_{CPU}/4$, $f_{CPU}/8$ or an external frequency.

Caution: In Flash devices, Timer A functionality has the following restrictions:

- TAOC2HR and TAOC2LR registers are write only
- Input Capture 2 is not implemented
- The corresponding interrupts cannot be used (ICF2, OCF2 forced by hardware to zero)



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Figure 35. Counter Timing Diagram, internal clock divided by 4



Figure 36. Counter Timing Diagram, internal clock divided by 8

CPU CLOCK	
INTERNAL RESET	1
TIMER CLOCK	/
COUNTER REGISTER	FFFC FFFD 0000
TIMER OVERFLOW FLAG (TOF)	

Note: The MCU is in reset state when the internal reset signal is high, when it is low the MCU is running.



Figure 38. Input Capture Timing Diagram

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Figure 43. Pulse Width Modulation Mode Timing Example with 2 Output Compare Functions





10.3.3.6 Pulse Width Modulation Mode

Pulse Width Modulation (PWM) mode enables the generation of a signal with a frequency and pulse length determined by the value of the OC1R and OC2R registers.

Pulse Width Modulation mode uses the complete Output Compare 1 function plus the OC2R register, and so this functionality can not be used when PWM mode is activated.

In PWM mode, double buffering is implemented on the output compare registers. Any new values written in the OC1R and OC2R registers are taken into account only at the end of the PWM period (OC2) to avoid spikes on the PWM output pin (OCMP1).

Procedure

To use pulse width modulation mode:

- 1. Load the OC2R register with the value corresponding to the period of the signal using the formula in the opposite column.
- 2. Load the OC1R register with the value corresponding to the period of the pulse if (OLVL1=0 and OLVL2=1) using the formula in the opposite column.
- 3. Select the following in the CR1 register:
 - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC1R register.
 - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin after a successful comparison with the OC2R register.
- 4. Select the following in the CR2 register:
 - Set OC1E bit: the OCMP1 pin is then dedicated to the output compare 1 function.
 - Set the PWM bit.
 - Select the timer clock (CC[1:0]) (see Table 16 Clock Control Bits).



If OLVL1=1 and OLVL2=0 the length of the positive pulse is the difference between the OC2R and OC1R registers.

If OLVL1=OLVL2 a continuous signal will be seen on the OCMP1 pin.

The OC*i*R register value required for a specific timing application can be calculated using the following formula:

 $OCiR Value = \frac{t \cdot f_{CPU}}{PRESC} - 5$

Where:

t = Signal or pulse period (in seconds)

 $f_{CPU} = CPU \operatorname{clock} \operatorname{frequency} (\operatorname{in} \operatorname{hertz})$

PRESC = Timer prescaler factor (2, 4 or 8 depending on CC[1:0] bits, see Table 16)

If the timer clock is an external clock the formula is:

$$OCiR = t * f_{EXT} - 5$$

Where:

t

= Signal or pulse period (in seconds)

f_{EXT} = External timer clock frequency (in hertz)

The Output Compare 2 event causes the counter to be initialized to FFFCh (See Figure 43)

Notes:

- 1. After a write instruction to the OC*i*HR register, the output compare function is inhibited until the OC*i*LR register is also written.
- 2. The OCF1 and OCF2 bits cannot be set by hardware in PWM mode therefore the Output Compare interrupt is inhibited.
- 3. The ICF1 bit is set by hardware when the counter reaches the OC2R value and can produce a timer interrupt if the ICIE bit is set and the I bit is cleared.
- 4. In PWM mode the ICAP1 pin can not be used to perform input capture because it is disconnected to the timer. The ICAP2 pin can be used to perform input capture (ICF2 can be set and IC2R can be loaded) but the user must take care that the counter is reset each period and ICF1 can also generates interrupt if ICIE is set.
- 5. When the Pulse Width Modulation (PWM) and One Pulse Mode (OPM) bits are both set, the PWM mode is the only active one.

SERIAL PERIPHERAL INTERFACE (Cont'd)

10.4.3.3 Master Mode Operation

In master mode, the serial clock is output on the SCK pin. The clock frequency, polarity and phase are configured by software (refer to the description of the SPICSR register).

Note: The idle state of SCK must correspond to the polarity selected in the SPICSR register (by pulling up SCK if CPOL=1 or pulling down SCK if CPOL=0).

To operate the SPI in master mode, perform the following steps in order (if the SPICSR register is not written first, the SPICR register setting (MSTR bit) may be not taken into account):

1. Write to the SPICR register:

- Select the clock frequency by configuring the SPR[2:0] bits.
- Select the clock polarity and clock phase by configuring the CPOL and CPHA bits. Figure 48 shows the four possible configurations.
 Note: The slave must have the same CPOL and CPHA settings as the master.
- 2. Write to the SPICSR register:
 - Either set the SSM bit and set the SSI bit or clear the SSM bit and tie the SS pin high for the complete byte transmit sequence.
- 3. Write to the SPICR register:
 - Set the MSTR and SPE bits
 <u>Note</u>: MSTR and SPE bits remain set only if SS is high).

The transmit sequence begins when software writes a byte in the SPIDR register.

10.4.3.4 Master Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MOSI pin most significant bit first.

When data transfer is complete:

- The SPIF bit is set by hardware
- An interrupt request is generated if the SPIE bit is set and the interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

- 1. An access to the SPICSR register while the SPIF bit is set
- 2. A read to the SPIDR register.

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Note: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

10.4.3.5 Slave Mode Operation

In slave mode, the serial clock is received on the SCK pin from the master device.

To operate the SPI in slave mode:

- 1. Write to the SPICSR register to perform the following actions:
 - Select the clock polarity and clock phase by configuring the CPOL and CPHA bits (see Figure 48).
 Note: The slave must have the same CPOL and CPHA settings as the master.
 - Manage the SS pin as described in Section 10.4.3.2 and Figure 46. If CPHA=1 SS must be held low continuously. If CPHA=0 SS must be held low during byte transmission and pulled up between each byte to let the slave write in the shift register.
- 2. Write to the SPICR register to clear the MSTR bit and set the SPE bit to enable the SPI I/O functions.

10.4.3.6 Slave Mode Transmit Sequence

When software writes to the SPIDR register, the data byte is loaded into the 8-bit shift register and then shifted out serially to the MISO pin most significant bit first.

The transmit sequence begins when the slave device receives the clock signal and the most significant bit of the data on its MOSI pin.

When data transfer is complete:

- The SPIF bit is set by hardware
- An interrupt request is generated if SPIE bit is set and interrupt mask in the CCR register is cleared.

Clearing the SPIF bit is performed by the following software sequence:

1. An access to the SPICSR register while the SPIF bit is set.

2. A write or a read to the SPIDR register.

Notes: While the SPIF bit is set, all writes to the SPIDR register are inhibited until the SPICSR register is read.

The SPIF bit can be cleared during a second transmission; however, it must be cleared before the second SPIF bit in order to prevent an Overrun condition (see Section 10.4.5.2).

SERIAL PERIPHERAL INTERFACE (Cont'd)

Table 19. SPI Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0021h	SPIDR	MSB							LSB
002111	Reset Value	х	х	х	х	х	х	х	х
0000h	SPICR	SPIE	SPE	SPR2	MSTR	CPOL	CPHA	SPR1	SPR0
0022n	Reset Value	0	0	0	0	х	х	х	х
00026	SPICSR	SPIF	WCOL	OR	MODF		SOD	SSM	SSI
002311	Reset Value	0	0	0	0	0	0	0	0



SERIAL COMMUNICATIONS INTERFACE (Cont'd)

Figure 51. SCI Block Diagram



Δ7/



Figure 86. 42-Pin Plastic Dual In-Line Package, Shrink 600-mil Width

Figure 87. 44-Pin Thin Quad Flat Package



Δ7/

Figure 88.

13.2 THERMAL CHARACTERISTICS

Symbol	Ratings	Value	Unit
R _{thJA}	Package thermal resistance (junction to ambient) TQFP32 7x7 SDIP32 400mil	70 TBD	°C/W
PD	Power dissipation ¹⁾	500	mW
T _{Jmax}	Maximum junction temperature ²⁾	150	°C

Notes:

<u>ل</u>حک

1. The power dissipation is obtained from the formula $P_D = P_{INT} + P_{PORT}$ where P_{INT} is the chip internal power ($I_{DD}xV_{DD}$) and P_{PORT} is the port power dissipation determined by the user. 2. The average chip-junction temperature can be obtained from the formula $T_J = T_A + P_D x$ RthJA.

14 ST7232A DEVICE CONFIGURATION AND ORDERING INFORMATION

Each device is available for production in user programmable versions (FLASH) as well as in factory coded versions (ROM). ST7232A devices are ROM versions. ST72P32A devices are Factory Advanced Service Technique ROM (FASTROM) versions: they are factory-programmed HDFlash devices. FLASH devices are shipped to customers with a default content (FFh), while ROM factory coded parts contain the code supplied by the customer. This implies that FLASH devices have to be configured by the customer using the Option Bytes while the ROM devices are factory-configured.

14.1 FLASH OPTION BYTES

	STATIC OPTION BYTE 0								STATIC OPTION BYTE 1							
	7 0					0	7							0		
	W	DG	irved	irved	irved	Irved	Irved	ш	5	C	OSCTYPE		OSCRANGE			DFF
	НАLТ	SW	Rese	Rese	Rese	Rese	Rese	FMF	PK	RS	1	0	2	1	0	PLLO
Default	1	1	1	0	0	1	1	1	0	1	1	0	1	1	1	1

The option bytes allows the hardware configuration of the microcontroller to be selected. They have no address in the memory map and can be accessed only in programming mode (for example using a standard ST7 programming tool). The default content of the FLASH is fixed to FFh. To program directly the FLASH devices using ICP, FLASH devices are shipped to customers with an internal clock source. In masked ROM devices, the option bytes are fixed in hardware by the ROM code (see option list).

OPTION BYTE 0

OPT7= **WDG HALT** Watchdog reset on HALT This option bit determines if a RESET is generated when entering HALT mode while the Watchdog is active.

0: No Reset generation when entering Halt mode

1: Reset generation when entering Halt mode

OPT6= **WDG SW** Hardware or software watchdog This option bit selects the watchdog type.

0: Hardware (watchdog always enabled)

1: Software (watchdog to be enabled by software)

OPT5:1 = Reserved, must be kept at default value.

OPT0= **FMP_R** *Flash memory read-out protection* Read-out protection, when selected, provides a protection against Program Memory content extraction and against write access to Flash memory.

Erasing the option bytes when the FMP_R option is selected causes the whole user memory to be erased first, and the device can be reprogrammed. Refer to Section 7.3.1 on page 37 and the ST7 Flash Programming Reference Manual for more details.

0: Read-out protection enabled

1: Read-out protection disabled

ST7232A DEVICE CONFIGURATION AND ORDERING INFORMATION (Cont'd)	
	0011001	

	ST7232A MICROCO (Last update:	NTROLLER OPTION LIST 16 December 2005)				
Customer:						
Address:						
Contact:						
Phone No:		•••				
Reference/ROM Code* :						
*The ROM code name is assi BOM code must be sent in S	igned by STMicroelectroni 19 format Hex extension	CS. cannot be processed				
Device Type/Memory Size/Pa	ackage (check only one op	tion):				
ROM DEVICE:	4K	8K				
TQFP32 7x7:	[] ST7232AK1T	[] ST7232AK2T				
SDIP32 ⁽³⁾ : I	[] ST7232AK1B	[] ST7232AK2B				
TQFP44 10x10:	[] ST7232AJ1T	[] ST7232AJ2T				
SDIP42 (%):	[]ST7232AJ1B	[]ST/232AJ2B				
DIE FORM:	4K	8K				
32-pin: I 44-pin: I	[] []					
Conditioning (check only one	option):					
Packaged	Product	Die Product (dice tested at 25°C only)				
TQFP: []Tape & R	eel []Trav	I Tape & Reel				
SDIP [] Tube		I [] Inked wafer				
		[] Sawn wafer on sticky foil				
Power Supply Bange: [] 3.8	3 to 5.5V					
Version/Temp. Range (do no	t check for die product). Pl	ease refer to datasheet for specific sales conditions:				
	······					
Standard ' Autom	otive I Temp. Range					
[]	0°C to +70°C					
[]	-10°C to +85°C					
	-40°C to +85°C					
	-40°C to +105°C					
' []	1 -40°C 10 +125°C	,				
Special Marking: [Authorized characters are let Clock Source Selection:] No [] Yes " ters, digits, '.', '-', '/' and spa	" (TQFP32 7 char., other pkg. 10 char. max) aces only.				
[] Resonator:	[] LP: Low power rea	sonator (1 to 2 MHz)				
	[] MP: Medium powe	er resonator (2 to 4 MHz)				
	[] MS: Medium spee	ed resonator (4 to 8 MHz)				
[] External Clo	ск ⁽¹⁾					
PLL ⁽¹⁾	[] Disabled	[] Enabled				
Reset Delay	[] 256 Cycles	[] 4096 Cycles				
Watchdog Selection: Watchdog Reset on Halt:	[] Software Activatic [] Reset	n [] Hardware Activation [] No Reset				
Readout Protection ⁽²⁾ :	[] Disabled	[] Enabled				
Date		Signature				
 (1) PLL not supported with ex (2) The Readout Protection b will differ between ROM and (3) Not available for Automoti 	tternal clock source inary value is inverted bet FLASH. ve. sion of this option list fro	ween ROM and FLASH products. The option byte checksum				
p://www.st.com/mcu > downloads > ST7 microcontrollers > Option list						

